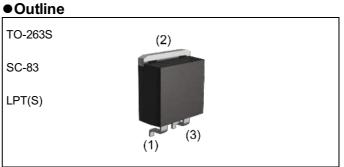
## Nch 800V 8A Power MOSFET

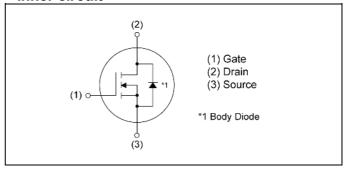
V <sub>DSS</sub>	800V
R <sub>DS(on)</sub> (Max.)	1.03Ω
I <sub>D</sub>	±8A
$P_D$	195W



## Features

- 1) Low on-resistance.
- 2) Fast switching speed.
- 3) Gate-source voltage ( $V_{\mbox{GSS}}$ ) guaranteed to be ±30V.
- 4) Drive circuits can be simple.
- 5) Parallel use is easy.
- 6) Pb-free plating; RoHS compliant

# ●Inner circuit



Packaging specifications

or dokaging opcomoduone				
	Packing	Embossed Tape		
	Reel size (mm)	330		
Type	Tape width (mm)	24		
	Quantity (pcs)	1000		
	Taping code	TL		
	Marking	R8008ANJ		

# Application

**Switching Power Supply** 

# ● **Absolute maximum ratings** (T<sub>a</sub> = 25°C ,unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain - Source voltage	V <sub>DSS</sub>	800	V
Continuous drain current (T <sub>c</sub> = 25°C)	I <sub>D</sub> *1	±8	Α
Pulsed drain current	I <sub>DP</sub> *2	±32	Α
Gate - Source voltage	V <sub>GSS</sub>	±30	V
Avalanche current, single pulse	I <sub>AS</sub> *3	4	Α
Avalanche energy, single pulse	E <sub>AS</sub> *3	4.2	mJ
Power dissipation (T <sub>c</sub> = 25°C)	P <sub>D</sub>	195	W
Junction temperature	T <sub>j</sub>	150	°C
Operating junction and storage temperature range	T <sub>stg</sub>	-55 to +150	°C

## ●Thermal resistance

Davamatav	Cymah al	Values			1.1-:4
Parameter	Symbol	Min.	Тур.	Max.	Unit
Thermal resistance, junction - case	R <sub>thJC</sub>	-	-	0.64	°C/W
Thermal resistance, junction - ambient	R <sub>thJA</sub>	-	-	80	°C/W
Soldering temperature, wavesoldering for 10s	T <sub>sold</sub>	-	-	265	°C

# ●Electrical characteristics (T<sub>a</sub> = 25°C)

Parameter	Cumb al	Conditions	Values			Unit
- Farameter	Symbol	Conditions	Min.	Тур.	Max.	Offic
Drain - Source breakdown voltage	V <sub>(BR)DSS</sub>	$V_{GS} = 0V$ , $I_D = 1mA$	800	-	-	V
		V <sub>DS</sub> = 800V, V <sub>GS</sub> = 0V				
Zero gate voltage drain current	I <sub>DSS</sub>	$T_j = 25^{\circ}C$	-	0.1	100	μΑ
		T <sub>j</sub> = 125°C	-	-	-	
Gate - Source leakage current	I <sub>GSS</sub>	$V_{GS} = \pm 30V, V_{DS} = 0V$	-	-	±100	nA
Gate threshold voltage	$V_{GS(th)}$	V <sub>DS</sub> = 10V, I <sub>D</sub> = 1mA	3	-	5	V
		V <sub>GS</sub> = 10V, I <sub>D</sub> = 4.0A				
Static drain - source on - state resistance	R <sub>DS(on)</sub> *4	$T_j = 25^{\circ}C$	-	0.79	1.03	Ω
		$T_j = 125^{\circ}C$	-	1.54	-	
Gate resistance	$R_{G}$	f = 1MHz, open drain	-	6.6	-	Ω

# ● Electrical characteristics (T<sub>a</sub> = 25°C)

Davamatar	Cymah al	Conditions	Values			Unit
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Forward Transfer Admittance	Y <sub>fs</sub>  *4	V <sub>DS</sub> = 10V, I <sub>D</sub> = 4A	2.0	4.0	-	S
Input capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0V	-	1100	-	
Output capacitance	C <sub>oss</sub>	V <sub>DS</sub> = 25V	-	500	-	pF
Reverse transfer capacitance	C <sub>rss</sub>	f = 1MHz	-	35	1	
Turn - on delay time	t <sub>d(on)</sub> *4	V <sub>DD</sub> ≈ 400V, V <sub>GS</sub> = 10V	-	30	-	
Rise time	t <sub>r</sub> *4	I <sub>D</sub> = 4.0A	-	35	-	no
Turn - off delay time	t <sub>d(off)</sub> *4	$R_L \simeq 100\Omega$	-	90	1	ns
Fall time	t <sub>f</sub> *4	$R_G = 10\Omega$	-	30	-	

# ● Gate charge characteristics (T<sub>a</sub> = 25°C)

Parameter	Cumphal	Conditions	Values			l limit
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Total gate charge	Qg*4	V <sub>DD</sub> ≈ 400V	-	38	-	
Gate - Source charge	Q <sub>gs</sub> *4	I <sub>D</sub> = 8A	-	8	-	nC
Gate - Drain charge	Q <sub>gd</sub> *4	V <sub>GS</sub> = 10V	-	19	-	
Gate plateau voltage	V <sub>(plateau)</sub>	V <sub>DD</sub> ≈ 400V, I <sub>D</sub> = 8A	-	7.0	-	V

<sup>\*1</sup> Limited only by maximum temperature allowed.

<sup>\*2</sup> Pw  $\leq$  10µs, Duty cycle  $\leq$  1%

<sup>\*3</sup> L $^{\sim}$ 500 $\mu$ H, V<sub>DD</sub>=50V, R<sub>G</sub>=25 $\Omega$ , starting T $_{j}$ =25 $^{\circ}$ C

<sup>\*4</sup> Pulsed

# ●Body diode electrical characteristics (Source-Drain) (T<sub>a</sub> = 25°C)

Darameter	Symbol	Conditions	Values			Unit
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Continuous forward current	I <sub>S</sub> *1	T - 25°C	1	1	8	А
Pulse forward current	I <sub>SP</sub> *2	T <sub>C</sub> = 25°C	-	-	32	А
Forward voltage	V <sub>SD</sub> *4	V <sub>GS</sub> = 0V, I <sub>S</sub> = 8A	-	-	1.5	V
Reverse recovery time	t <sub>rr</sub> *4		-	625	-	ns
Reverse recovery charge	Q <sub>rr</sub> *4	I <sub>S</sub> = 8A, V <sub>GS</sub> = di/dt = 100A/µs	-	7.03	-	μC
Peak reverse recovery current	I <sub>rrm</sub> *4	- α, ατ 100/ γμο	-	22.5	-	Α

# Typical transient thermal characteristics

Symbol	Value	Unit
R <sub>th1</sub>	0.325	
R <sub>th2</sub>	2.126	K/W
R <sub>th3</sub>	72.40	

Symbol	Value	Unit
C <sub>th1</sub>	0.00702	
C <sub>th2</sub>	0.0174	Ws/K
C <sub>th3</sub>	0.782	

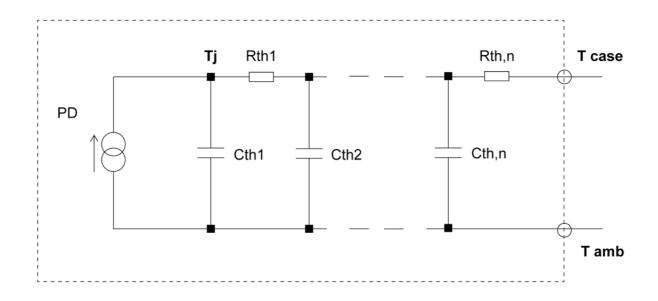


Fig.1 Power Dissipation Derating Curve

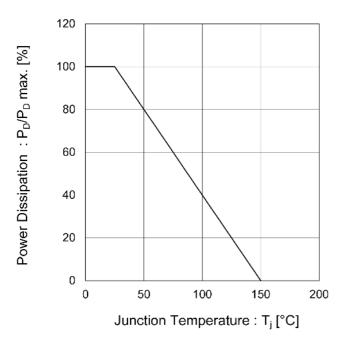
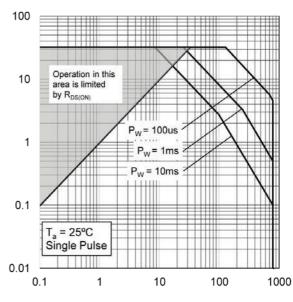


Fig.2 Maximum Safe Operating Area



Drain Current : I<sub>D</sub> [A]

Drain - Source Voltage: VDS [V]

Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

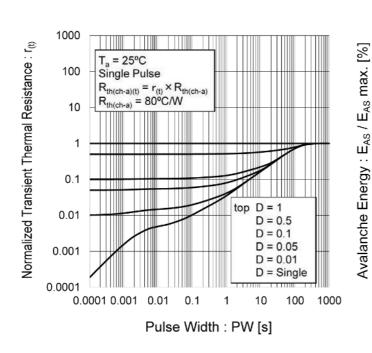


Fig.4 Avalanche Energy Derating Curve vs. Junction Temperature

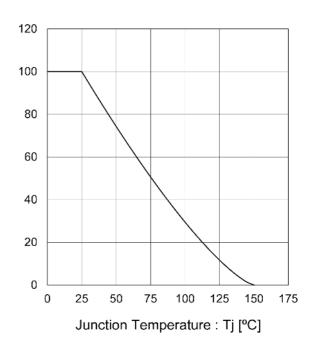
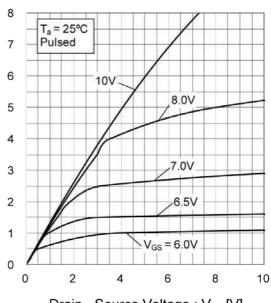


Fig.5 Typical Output Characteristics(I)

8 T<sub>a</sub> = 25°C Pulsed 7 6 Drain Current : I<sub>D</sub> [A] 8.0V 5 4 7.0V 3 6.5V 2 1  $V_{GS} = 6.0V$ 0 0 10 20 30 40 50 Drain - Source Voltage: VDS [V]

Fig.6 Typical Output Characteristics(II)



Drain Current: Ip [A]

Drain - Source Voltage : V<sub>DS</sub> [V]

Fig.7 Tj = 150°C Typical Output Characteristics (I)

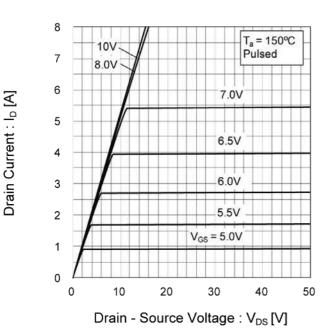
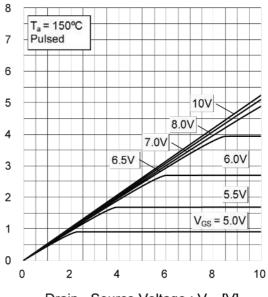


Fig.8 Tj = 150°C Typical Output Characteristics (II)



 $Drain - Source\ Voltage: V_{DS}[V]$ 

Drain Current: Ip [A]

Fig.9 Normalized Breakdown Voltage vs.

Junction Temperature

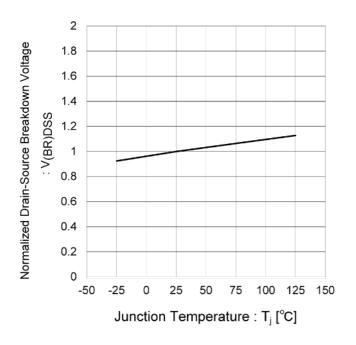


Fig.10 Typical Transfer Characteristics

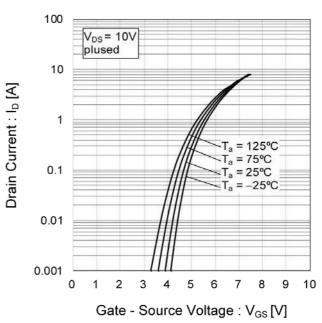


Fig.11 Normalized Gate Threshold Voltage vs. Junction Temperature

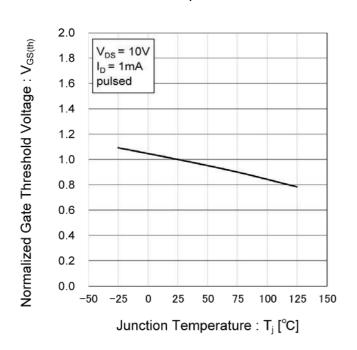


Fig.12 Forward Transfer Admittance vs. Drain Current

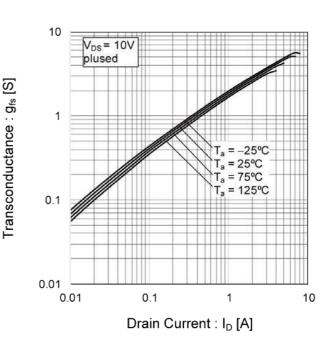


Fig.13 Static Drain - Source On - State Resistance vs. Gate Source Voltage

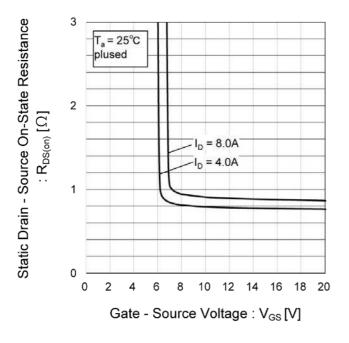


Fig.14 Static Drain - Source On - State Resistance vs. Junction Temperature

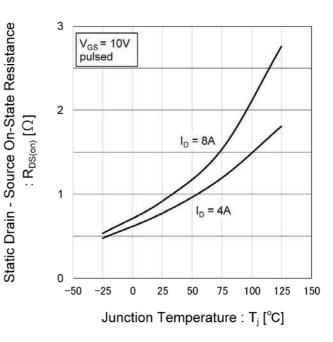


Fig.15 Static Drain - Source On - State Resistance vs. Drain Current

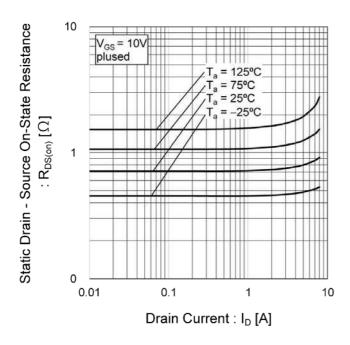
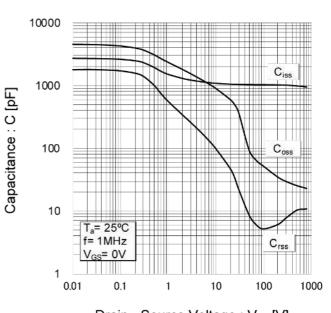


Fig.16 Typical Capacitance vs. Drain - Source Voltage



Drain - Source Voltage :  $V_{DS}[V]$ 

Fig.17 Switching Characteristics

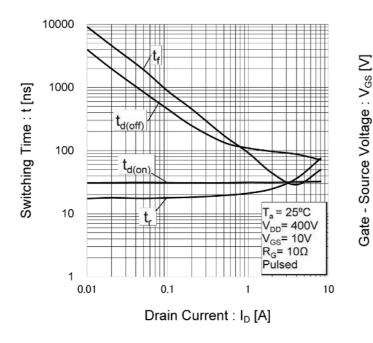


Fig.18 Dynamic Input Characteristics

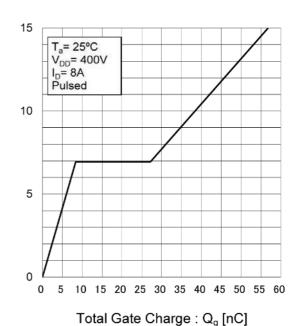


Fig.19 Inverse Diode Forward Current vs. Source - Drain Voltage

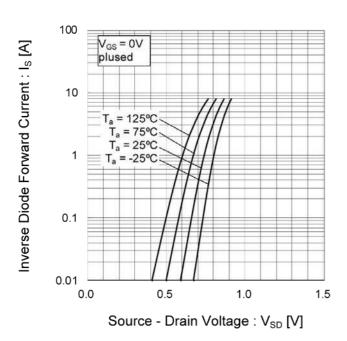
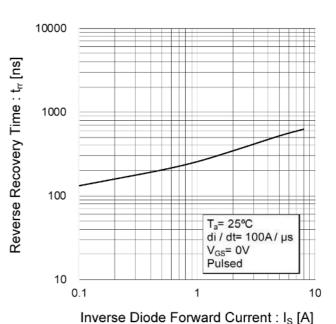


Fig.20 Reverse Recovery Time vs. Inverse Diode Forward Current



#### Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

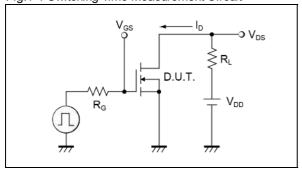


Fig.2-1 Gate Charge Measurement Circuit

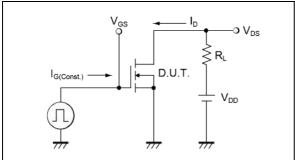


Fig.3-1 Avalanche Measurement Circuit

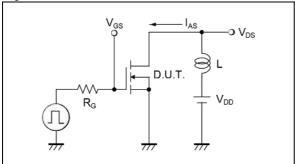


Fig.4-1 dv/dt Measurement Circuit

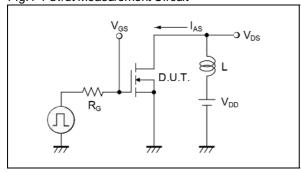


Fig.5-1 di/dt Measurement Circuit

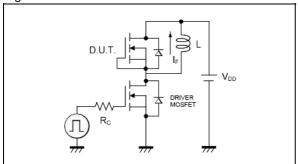


Fig.1-2 Switching Waveforms

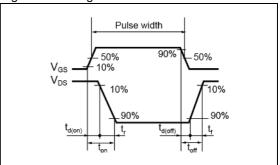


Fig.2-2 Gate Charge Waveform

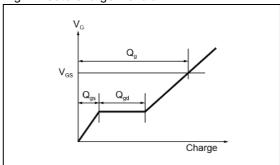


Fig.3-2 Avalanche Waveform

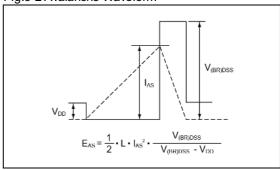


Fig.4-2 dv/dt Waveform

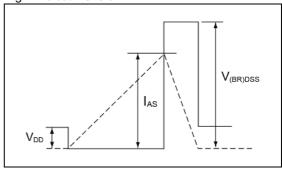
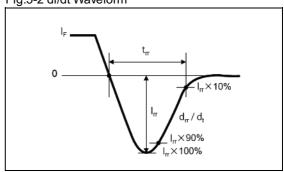
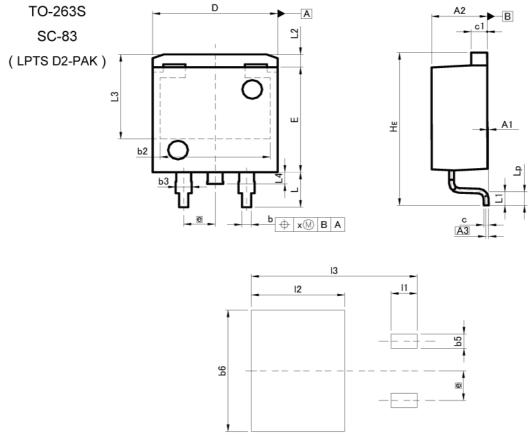


Fig.5-2 di/dt Waveform



# Dimensions



Pattern of terminal position areas [Not a pattern of soldering pads]

D114	MILIM	FTERS	INC	HES
DIM	MIN	MAX	MIN	MAX
A1	0.00	0.30	0.000	0.012
A2	4.30	4.70	0.169	0.185
A3	0.	25	0.0	10
b	0.68	0.98	0.027	0.039
b2	8.	90	0.3	50
b3	1.14	1.44	0.045	0.057
С	0.30	0.60	0.012	0.024
c1	1.10	1.50	0.043	0.059
D	9.80	10.40	0.386	0.409
E	8.80	9.20	0.346	0.362
е	2.	54	0.100	
HE	12.80	13.40	0.504	0.528
L	2.70	3.30	0.106	0.130
L1	1.20		0.0	47
L2	1.10		0.0	43
L3	7.	25	0.285	
L4	1.00		0.0	39
Lp	0.90	1.50	0.035	0.059
Х	=	0.25	175 ),	0.010
5m4	MILIM	FTFRS	INC	HFS
DIM  -	NATA I	MAN	MATAL	MAN

DIM	MILIM	ETERS	INCHES		
	MIN	MAX	MIN	MAX	
b5	=(	1.23	-	0.049	
b6		10.40	; <del>=</del>	0.409	
	<u>22</u> 0	2.10		0.083	
12	EX.	7.55	i <del>lla</del>	0.297	
13		13.40	-	0.528	

Dimension in mm/inches



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(Note1) Medical Equipment Classification of the Specific Applications

JAPAN	USA	EU	CHINA
CLASSⅢ	CLASSII	CLASS II b	CLASSIII
CLASSIV		CLASSⅢ	

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  - [b] Installation of redundant circuits to reduce the impact of single or multiple circuit failure
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  - [b] Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
  - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl<sub>2</sub>, H<sub>2</sub>S, NH<sub>3</sub>, SO<sub>2</sub>, and NO<sub>2</sub>
  - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
  - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
  - [f] Sealing or coating our Products with resin or other coating materials
  - [g] Use of our Products without cleaning residue of flux (Exclude cases where no-clean type fluxes is used. However, recommend sufficiently about the residue.); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
  - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse, is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

#### Precaution for Mounting / Circuit board design

- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

#### **Precautions Regarding Application Examples and External Circuits**

- 1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
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#### **Precaution for Electrostatic**

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

### **Precaution for Storage / Transportation**

- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
  - [a] the Products are exposed to sea winds or corrosive gases, including Cl2, H2S, NH3, SO2, and NO2
  - [b] the temperature or humidity exceeds those recommended by ROHM
  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
- Even under ROHM recommended storage condition, solderability of products out of recommended storage time period
  may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is
  exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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